

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yu-Lun Liu</td> <td>10/30/2012</td> </tr> <tr> <td>Chia-Chu Liu</td> <td>10/30/2012</td> </tr> <tr> <td>Kuei-Shun Chen</td> <td>10/30/2012</td> </tr> <tr> <td>Chung-Ming Wang</td> <td>10/30/2012</td> </tr> <tr> <td>Chie-Chieh Lin</td> <td>10/30/2012</td> </tr> </tbody> </table>		Name	Execution Date	Yu-Lun Liu	10/30/2012	Chia-Chu Liu	10/30/2012	Kuei-Shun Chen	10/30/2012	Chung-Ming Wang	10/30/2012	Chie-Chieh Lin	10/30/2012
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<table border="1"> <tr> <td>Name:</td> <td>Taiwan Semiconductor Manufacturing Company, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Road 6</td> </tr> <tr> <td>Internal Address:</td> <td>Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	Street Address:	No. 8, Li-Hsin Road 6	Internal Address:	Science-Based Industrial Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77
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PROPERTY NUMBERS Total: 1													
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CORRESPONDENCE DATA													
<p>Fax Number: 2142000853  <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 214-651-5000        Email: ipdocketing@haynesboone.com        Correspondent Name: Haynes and Boone LLP        Address Line 1: 2323 Victory Avneue        Address Line 2: Suite 700        Address Line 4: Dallas, TEXAS 75219</p>													
ATTORNEY DOCKET NUMBER:	2012-0142/24061.2139												

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NAME OF SUBMITTER:

David M. O'Dell

Total Attachments: 3

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Docket No.: 2012-0142 / 24061.2139

Customer No.: 42717

**ASSIGNMENT**

WHEREAS, we,

- |     |                 |    |  |
|-----|-----------------|----|--|
| (1) | Yu-Lun Liu      | of | No. 36, Hebin Street, Beidou Township<br>Changhua County 521, Taiwan, R.O.C. |
| (2) | Chia-Chu Liu    | of | 8F, No. 177, Ba-der Road<br>Shin-Chu City, Taiwan, R.O.C.                    |
| (3) | Kuei-Shun Chen  | of | 27 393 Ln, Min-Hu Road<br>Hsin-Chu, Taiwan 300, R.O.C.                       |
| (4) | Chung-Ming Wang | of | No. 288, Minsheng N. Rd., West District<br>Chiayi City 600, Taiwan, R.O.C.   |
| (5) | Chie-Chieh Lin  | of | No.69, Honghua St., Luzhu Township, Taoyuan County<br>338, Taiwan (R.O.C.)   |

have invented certain improvements in

**METHOD FOR IMPROVING RESIST PATTERN PEELING**

for which we have executed an application for Letters Patent of the United States of America, filed on November 1, 2012, and assigned application no. 13/666,107 and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

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AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Inventor Name: Yu-Lun Liu

Residence Address: No. 36, Hebin Street, Beidou Township  
Changhua County 521, Taiwan, R.O.C.

Dated: 2012.10.30

Yu-Lun Liu  
Inventor Signature

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Inventor Name: Chia-Chu Liu

Residence Address: 8F, No. 177, Ba-der Road  
Shin-Chu City, Taiwan, R.O.C.

Dated:

Chia-Chu Liu  
2012.10.30


Chia-Chu Liu  
Inventor Signature

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Inventor Name: Kuei-Shun Chen  
Residence Address: 27 393 Ln, Min-Hu Road  
Hsin-Chu, Taiwan 300, R.O.C.

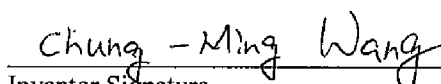
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Inventor Name: Chung-Ming Wang  
Residence Address: No. 288, Minsheng N. Rd., West District  
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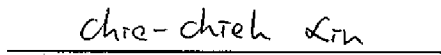
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Inventor Name: Chie-Chieh Lin  
Residence Address: No.69, Honghua St., Luzhu Township,  
Taoyuan County 338, Taiwan (R.O.C.)

Dated: 2012/10/30

  
Inventor Signature